### 501878643 04/05/2012

#### PATENT ASSIGNMENT

## Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Hideo Kawabe	02/21/2012
Masatoshi Ueno	02/27/2012
Shinobu Kuriya	02/27/2012
Yusaku Kato	02/27/2012
Kenichi Kabasawa	02/28/2012
Tetsuro Goto	02/17/2012
Tsubasa Tsukahara	02/29/2012
Toshiyuki Nakagawa	02/24/2012

#### **RECEIVING PARTY DATA**

Name:	Sony Corporation
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13435336

#### **CORRESPONDENCE DATA**

**Fax Number**: (617)646-8646 **Phone**: 6176468000

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via US Mail.

Correspondent Name: Wolf Greenfield & Sacks, P.C.

Address Line 1: 600 Atlantic Avenue

Address Line 4: Boston, MASSACHUSETTS 02210

**PATENT** 

REEL: 027993 FRAME: 0575

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ATTORNEY DOCKET NUMBER:	S1459.71204US00
NAME OF SUBMITTER:	Helen K. Kim
Total Attachments: 4 source=Executed Assignment 71204#page source=Executed Assignment 71204#page source=Executed Assignment 71204#page source=Executed Assignment 71204#page	2.tif 3.tif

PATENT REEL: 027993 FRAME: 0576

Attorney Docket No. S1459,71204US00 SONY Ref. No.: SP310881US00

#### ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in OPERATION APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are nereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest theoreto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this	application to insert the serial number and filing date of this application in
the spaces that follow: Serial Number: 13/435,3210	, Piling Date: <u>North 30, 2012</u>
This assignment executed on the dates indicated below.	
HIDEO KAWABE	
Name of first or sole inventor	Execution date of U.S. Patent Application
SAITAMA, JAPAN	
Residence of First or sole inventor/ Hileo Kawabe	Feb 21,2012
Signature of first or sole inventor	Date of this assignment
MASATOSHI UENO	
Name of second inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	PP
Residence of second inventor	
Signature of second inventor	Date of this assignment
SHINOBU KURIYA	
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of third inventor	
Signature of third inventor	Date of this assignment

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# ADDITIONAL INVENTOR(S)

YUSAKU KATO	
Name of fourth inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of fourth inventor	t
Signature of fourth inventor	Teb 27, 2012
Signature of fourth inventor	Date of this assignment
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KENICHI KABASAWA	
Name of fifth inventor	Execution date of U.S. Patent Application
SAITAMA, JAPAN	
Residence of fifth inventor	F / O > A
Kenichi Kapasawa	Date of this assignment
Signature of fifth inventor	Date of this assignment
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TETSURO GOTO	
Name of sixth inventor	Execution date of U.S. Patent Application
	Execution date of 0.5. Patent Application
KANAGAWA, JAPAN Residence of sixth inventor	
Residence of Sixth inventor	
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Signature of sixth inventor	Date of this assignment
TSUBASA TSUKAHARA	
Name of seventh inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of seventh inventor	
Signature of seventh inventor	Date of this assignment
Signature of Seventi Inventor	Date of this assignment
TOOLINGINGS	
TOSHIYUKI NAKAGAWA	
Name of eighth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment
Name of ninth inventor	Execution date of U.S. Patent Application
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Residence of ninth inventor	
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Signature of ninth inventor	Date of this assignment

#### Attorney Docket No. S1459.71204US00 SONY Ref. No.: SP310881US00

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WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in OPERATION APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record i	in this application to insert the serial number and filing date of this application i
the spaces that follow: Scrial Number:13/435,	330, Filing Date: Werch 30, 2012
This assignment executed on the dates indicated below.	
HIDEO KAWABE	
Name of first or sole inventor SAITAMA, JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor	
Signature of first or sole inventor	Date of this assignment
MASATOSHI UENO	
Name of second inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of second inventor  Signature of second inventor	Johnson 27. 20/2 Date of this assignment
SHINOBU KURİYA	Date of this assignment
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of third inventor	
Shinoln Kuriun	_ February 27. 2012
Signature of third inventor .	Date of this assignment

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## ADDITIONAL INVENTOR(S)

YUSAKU KATO	
Name of fourth inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of fourth inventor	
Signature of fourth inventor	Date of this assignment
KENICHI KABASAWA	
Name of fifth inventor	Execution date of U.S. Patent Application
SAITAMA, JAPAN	Execution date of 0.5.1 atom Approaction
Residence of fifth inventor	The state of the s
Signature of fifth inventor	Date of this assignment
TETSURO GOTO	
Name of sixth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of sixth inventor	He is the same of
Tetsuro Goto	February 17, 2012  Date of this assignment
Signature of sixth inventor	Date of this assignment
MONTH OF MONTH AND A	
TSUBASA TSUKAHARA	E ( ) L CYLG D ( ) A L
Name of seventh inventor	Execution date of U.S. Patent Application
Name of seventh inventor TOKYO, JAPAN	Execution date of U.S. Patent Application
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Name of seventh inventor TOKYO, JAPAN Residence of seventh inventor	Execution date of U.S. Patent Application  Leb 29, 20/2  Date of this assignment
Name of seventh inventor TOKYO, JAPAN Residence of seventh inventor Success Success	0 1
Name of seventh inventor TOKYO, JAPAN Residence of seventh inventor Sugar Suga	0 1
Name of seventh inventor TOKYO, JAPAN Residence of seventh inventor Signature of seventh inventor TOSHIYUKI NAKAGAWA	Leb 29, 20/2 Date of this assignment
Name of seventh inventor TOKYO, JAPAN Residence of seventh inventor Succession Supplies Signature of seventh inventor	0 1
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor	Leb 29, 20/2 Date of this assignment
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hashwirkin Paleagawa	Leb 29, 20/2 Date of this assignment  Execution date of U.S. Patent Application
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor	Leb 29, 20/2 Date of this assignment
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hashwirkin Paleagawa	Leb 29, 20/2 Date of this assignment  Execution date of U.S. Patent Application
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hashwirkin Paleagawa	Date of this assignment  Execution date of U.S. Patent Application
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hamman Palaman  Signature of eighth inventor	Date of this assignment  Execution date of U.S. Patent Application  Melmany 24, 20/2  Date of this assignment
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hashwirkin Paleagawa	Date of this assignment  Execution date of U.S. Patent Application
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hashuyuku Pakagawa  Signature of eighth inventor	Leb 29, 20/2 Date of this assignment  Execution date of U.S. Patent Application  Melway 24, 20/2 Date of this assignment
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hamman Palaman  Signature of eighth inventor	Leb 29, 20/2 Date of this assignment  Execution date of U.S. Patent Application  Melway 24, 20/2 Date of this assignment
Name of seventh inventor  TOKYO, JAPAN  Residence of seventh inventor  Signature of seventh inventor  TOSHIYUKI NAKAGAWA  Name of eighth inventor  KANAGAWA, JAPAN  Residence of eighth inventor  Hashuyuku Pakagawa  Signature of eighth inventor	Leb 29, 20/2 Date of this assignment  Execution date of U.S. Patent Application  Melway 24, 20/2 Date of this assignment

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PATENT REEL: 027993 FRAME: 0580